



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20261008000.1	PCN Issued	October 09, 2026
Qualify TI Mexico (TIWM) as an additional Assembly site for select package devices		Sample request deadline:	December 08, 2026
		Estimated 1st ship date:	January 07, 2027
Sample requests received after December 08, 2026 will not be supported.			

Change type(s)
Assembly Site
Packing/Shipping/Labeling

PCN Details

Description of Change:		
Texas Instruments is pleased to announce the qualification of TI Mexico (TIWM) as an alternate Assembly site for select devices in the USIP package. No material differences between sites.		
	Current	Additional
Assembly site	PTIAT	TIWM
Qual details are provided in the Qual Data Section.		
Reason for Change:	Continuity of supply.	

Anticipated impact on Form, Fit, Function, Quality or Reliability:	Request the Supporting Data Packet for more details on the changes.												
Impact on Environmental Ratings	<p>Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.</p> <table><tr><th>RoHS</th><th>REACH</th><th>Green Status</th><th>IEC 62474</th></tr><tr><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td></tr></table>	RoHS	REACH	Green Status	IEC 62474	☒ No Change	☒ No Change	☒ No Change	☒ No Change				
RoHS	REACH	Green Status	IEC 62474										
☒ No Change	☒ No Change	☒ No Change	☒ No Change										
Changes to product identification resulting from this PCN:	<div>Assembly Site Information<table><tr><th>Assembly Site</th><th>Assembly Site Origin (22L)</th><th>Assembly Country Code (23L)</th><th>Assembly City</th></tr><tr><td>PTIAT</td><td>PT2</td><td>TWN</td><td>Hsinchu</td></tr><tr><td>TIWM</td><td>PTM</td><td>MEX</td><td>Aguascalientes</td></tr></table></div> <p>Sample product shipping label (not actual product label):</p> <div><p>(1P)PTAS2560YFFR (Q) 3000 (D) 1710 (31T) LOT: 7133710JCP (4W) SWR(1T) 2855550Z9A (P) (2P) REV: A0 (V) 0033317 (20L) CSO: DM6 (21L) CCO: USA (22L) ASO: JCP (23L) ACO: CHN</p></div>	Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City	PTIAT	PT2	TWN	Hsinchu	TIWM	PTM	MEX	Aguascalientes
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City										
PTIAT	PT2	TWN	Hsinchu										
TIWM	PTM	MEX	Aguascalientes										

Products Affected:			
TPSM82821ASILR	TPSM82822ASILR	TPSM82823ASILR	
TPSM82821SILR	TPSM82822SILR	TPSM82823SILR	

Qualification Data

Addition of TI MEXICO as Finishing Site for SIL USIP package family
 (Note: Substate manufacturing site is unchanged)
 Approve Date 06-October-2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qualification Device TI Mexico : <u>TPSM82823SILR</u>	Original Qualification: TPSM82823SILR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	3/231/0	3/231/0
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/231/0
ESD	E2	ESD CDM	-	1000 Volts	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	1/3/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device TPSM82823SILR is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2603-027

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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